REVISIONS			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Add vendor CAGE 27014. Add case outline E. Editorial and technical changes throughout.	96-05-22	M. A. FRYE
B	Add case outline X for CAGE 27014. Make changes to 1.2.4, theta JA, theta JC, as specified in 1.3, and figure 1. - ro	99-09-07	R. MONNIN

REV																			
SHEET																			
REV	B																		
SHEET	15																		

REV STATUS	REV	B	B	B	B	B	B	B	B	B	B	B	B	B	B	B
OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12	13	14	

PMIC N/A

PREPARED BY
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DRAWING APPROVAL DATE
95-12-21

REVISION LEVEL
B

DEFENSE SUPPLY CENTER COLUMBUS
COLUMBUS, OHIO 43216

STANDARD MICROCIRCUIT DRAWING

THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE

AMSC N/A

MICROCIRCUIT, LINEAR, LOW DROPOUT, -15 V VOLTAGE REGULATOR, MONOLITHIC

SILICON

SIZE	CAGE CODE	
A	67268	5962-95709

SHEET 1 OF 15

DSCC FORM 2233
APR 97

5962-E424-99

1. SCOPE

1.1 Scope. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.

1.2 PIN. The PIN is as shown in the following example:

5962	-	95709	01	Q	E	X
Federal stock class designator	RHA designator (see 1.2.1)		Device type (see 1.2.2)	Device class designator (see 1.2.3)	Case outline (see 1.2.4)	Lead finish (see 1.2.5)

Drawing number

1.2.1 RHA designator. Device classes Q and V RHA marked devices meet the MIL-PRF-38535 specified RHA levels and are marked with the appropriate RHA designator. Device class M RHA marked devices meet the MIL-PRF-38535, appendix A specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

Device type	Generic number	Circuit function
01	LM2990-15	Low dropout, -15 V voltage regulator

1.2.3 Device class designator. The device class designator is a single letter identifying the product assurance level as follows:

Device class	Device requirements documentation
M	Vendor self-certification to the requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A
Q or V	Certification and qualification to MIL-PRF-38535

1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	Terminals	Package style
E	GDIP1-T16 or CDIP2-T16	16	Dual-in-line
M	See figure 1	3	Surface mount package
N	See figure 1	3	Leadless, surface mount package
T	See figure 1	3	TO-257, flange mounted package with non-isolated tab, glass sealed
U	See figure 1	3	TO-257, flange mounted package with isolated tab, glass sealed
X	See figure 1	16	Gullwing flat pack
Y	MBFM1-P2	2	TO-3, flange mounted package
2	CQCC1-N20	20	Square leadless chip carrier

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

1.3 Absolute maximum ratings. 1/

Input voltage (V_{IN}) ..... -26 V to +0.3 V
Output voltage (V_{OUT}) ..... -15 V dc
Output current (I_{OUT}):
  Cases E, N, T, X, and Y ..... 1.5 A
  Cases M and U ..... 1.2 A
  Case 2 ..... 0.3 A
Internal power dissipation (P_D) ..... Internally limited 2/
Junction temperature (T_J) ..... +150°C
Storage temperature ..... -65°C to +150°C
Lead temperature (soldering, 10 seconds):
  Cases E and X ..... +260°C
  Cases M, N, T, U, Y, and 2 ..... +300°C
Thermal resistance, junction-to-case (θ_{JC}):
  Case E ..... 5°C/W
  Cases N, T, and X ..... 3°C/W
  Cases M and U ..... 4.2°C/W
  Cases Y and 2 ..... See MIL-STD-1835
Thermal resistance, junction-to-ambient (θ_{JA}):
  Case E ..... 75°C/W
  Cases M, N, T, U, and 2 ..... 42°C/W
  Case X ..... 119°C/W
  Case Y ..... 35°C/W

1.4 Recommended operating conditions.

Input voltage (V_{IN}) ..... -20 V
Ambient operating temperature range (T_A) ..... -55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-973 - Configuration Management.
MIL-STD-1835 - Interface Standard For Microcircuit Case Outlines.

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.
2/ The maximum power dissipation is a function of T_J, θ_{JA}, and T_A. The maximum allowable power dissipation at any ambient temperature is $P_D = (T_J - T_A) / \theta_{JA}$. If this dissipation is exceeded, the die temperature will rise above +125°C, and the device will eventually go into thermal shutdown at T_J of approximately 160°C

HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.3 Electrical performance characteristics and postirradiation parameter limits. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 Certification/compliance mark. The certification mark for device classes Q and V shall be a “QML” or “Q” as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

3.6 Certificate of compliance. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 Certificate of conformance. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change for device class M. For device class M, notification to DSCC-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions 1/ $-55°C \le T_A \le +125°C$ unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Output voltage	V_{OUT}	I_{OUT} = 5 mA to 1 A	1	01	-15.30	-14.70	V
			2,3		-15.75	-14.25	
Quiescent current	I_Q	$I_{OUT} \le 1$ A, 2/	1	01		15	mA
		V = -15 V	2,3			50	
		$I_{OUT} \le 1.0$ A 3/	1			5	
			2,3			10	
		I_{OUT} = 1 A, 3/ V_{IN} = -15 V	1,2,3			50	
Line regulation voltage	V_{RLN}	V_{IN} = -26 V to -16 V, 2/	1	01	-75	75	mV
		I_{OUT} = 5 mA	2,3		-120	120	
		$V_{IN} = V_{NOUT}$ - 1 V to - 26 V, I_{OUT} = 5 mA 3/	1,2,3		-60	60	
Load regulation voltage	V_{RLD}	I_{OUT} = 50 mA to 1 A 2/	1	01	-120	120	mV
			2,3		-190	190	
		I_{OUT} = 50 mA to 1 A 3/	1		-70	70	
			2,3		-100	100	
Dropout voltage	V_{DOUT}	I_{OUT} = 0.1 A, 2/ 3/ $\Delta V_{OUT} \le 100$ mV	1,2,3	01		0.3	V
		I_{OUT} = 1 A, 2/ 3/ $\Delta V_{OUT} \le 100$ mV				1	
Output noise voltage	V_{ON}	I_{OUT} = 5 mA, 2/ 4/ f = 10 Hz to 100 Hz	1,2,3	01		1800	µV
		I_{OUT} = 5 mA, 3/ f = 10 Hz to 100 kHz				1800	

See footnotes at end of table.

TABLE I. Electrical performance characteristics – Continued.

Test	Symbol	Conditions 1/ $-55°C \le T_A \le +125°C$ unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Short circuit current	I_{OS}	$R_L = 1.0\ \Omega$ 2/	1	01	0.60		A
			2,3		0.50		
		$R_L = 1.0\ \Omega$ 3/	1		0.75		
			2,3		0.60		
Maximum output current	I_{MAX}	$T_A = +25°C$ 3/	1	01	1.40		A
		$T_A = +25°C$ 2/			1.18		
Ripple rejection	RR	$V_{RIPPLE} = 1$ V rms, $I_{OUT} = 5$ mA, f = 1 kHz, $T_A = +25°C$	4	01	42		dB

1/ Input voltage (V_{IN}) = -20 V and output capacitance (C_{OUT}) = 47 µF.

2/ Applies to case outline U.

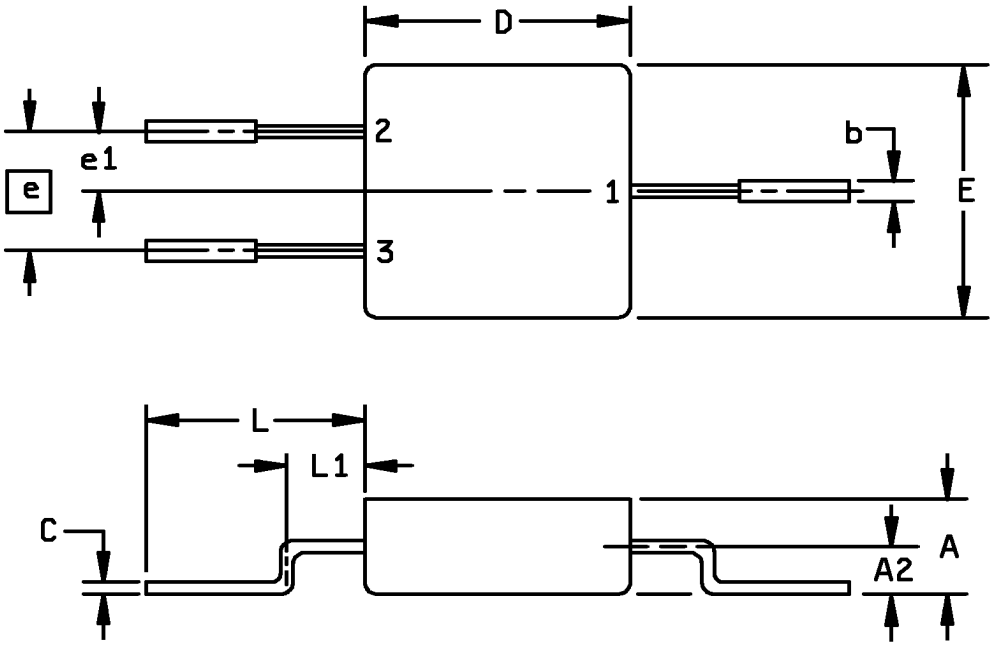
3/ Applies to case outline E.

4/ If not tested, shall be guaranteed to the limits specified in table I herein.

3.9 Verification and review for device class M. For device class M, DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 Microcircuit group assignment for device class M. Device class M devices covered by this drawing shall be in microcircuit group number 52 (see MIL-PRF-38535, appendix A).

Case M

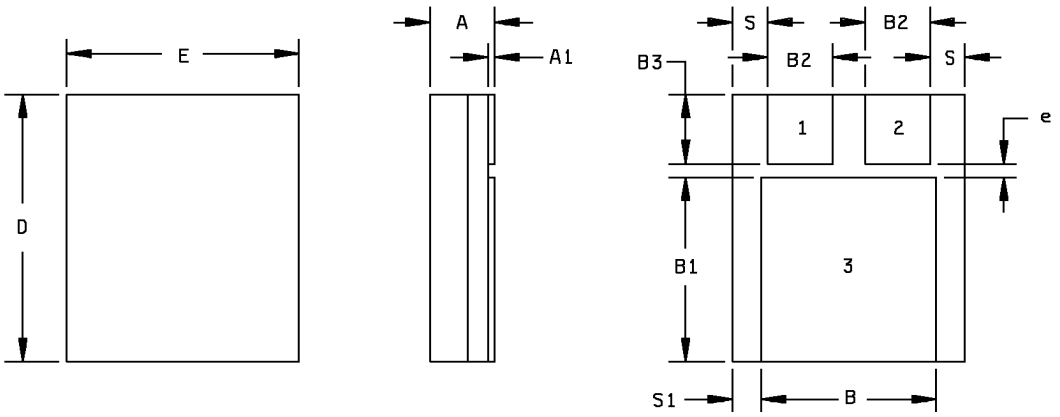


Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	.150	.170	3.81	4.32
A2	.070	.090	1.78	2.29
b		.035		.89
C	.020		.51	
D	.415	.435	10.54	11.05
E	.415	.435	10.54	11.05
e	.200 BSC		5.08 BSC	
e1	.100 BSC		2.54 BSC	
L	.350		8.89	
L1		.135		3.43

NOTE:
The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. Case outline.

Case outline N

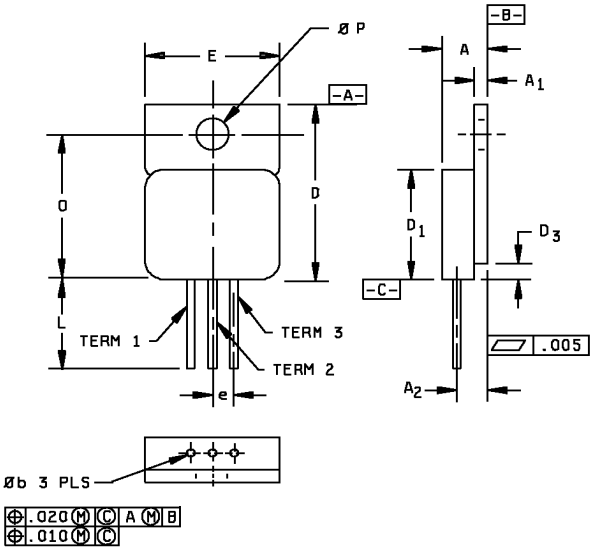


Dimension	Inches		Millimeters	
	Min	Max	Min	Max
A	.135	.145	3.43	3.68
A1	.010	.020	.25	.51
B	.370	.380	9.40	9.65
B1	.410	.420	10.41	10.67
B2	.135	.145	3.43	3.68
B3	.152	.162	3.86	4.11
D	.620	.630	15.75	16.00
E	.495	.505	12.57	12.83
e	.030		.76	
S	.070	.080	1.78	2.03
S1	.057	.067	1.45	1.70

NOTE:
The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. Case outline – Continued.

Cases T and U



Letter	Inches		Millimeters	
	Min	Max	Min	Max
A	.190	.200	4.83	5.08
A1	.035	.045	0.89	1.14
A2	.120 BSC		3.05 BSC	
ϕb	.025	.035	0.64	0.89
D	.645	.665	16.38	16.89
D1	.410	.430	10.41	10.92
D3	.000	.065	0.00	1.65
e	.100 BSC		2.54 BSC	
E	.410	.422	10.41	10.71
L	.500	.750	12.70	19.05
O	.527	.537	13.39	13.64
ϕP	.140	.150	3.56	3.81

NOTE:
The U.S. government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.

FIGURE 1. Case outline – Continued.

Case X

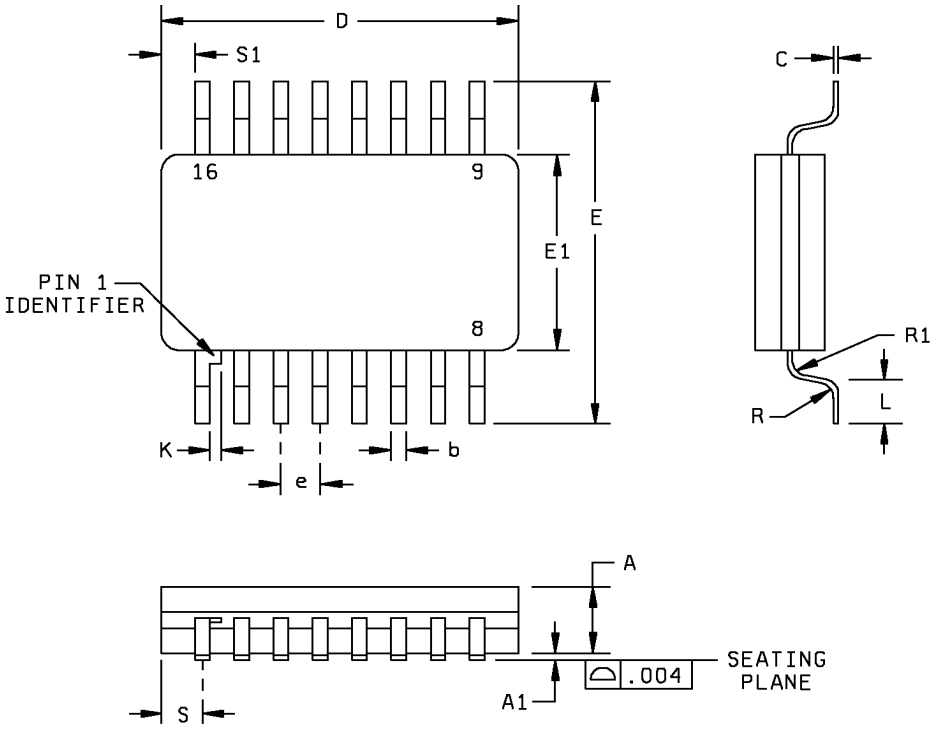


FIGURE 1. Case outlines – Continued.

Case X – continued.

Ltr	Inches		Millimeters		Notes
	Min	Max	Min	Max	
A	.050	.080	1.27	2.03	
A1	.004	.012	0.10	0.30	
b	.015	.019	0.38	0.48	2
C	.004	.008	0.10	0.20	2
D	---	.390	---	9.91	
E	.400	.420	10.16	10.67	
E1	.245	.270	6.22	6.86	
e	.050 BSC		1.27 BSC		
K	.008	.012	0.20	0.30	
L	.037	.043	0.94	1.09	
R	.013	.017	0.33	0.43	
R1	.013	.017	0.33	0.43	
S	---	.018	---	0.46	
S1	.005	---	0.13	---	

NOTES:
1. The US government preferred system of measurement is the metric SI system. However, since this item was originally designed using inch-pound units of measurement, in the event of conflict between the metric and inch-pound units, the inch-pound units shall take precedence.
2. Maximum limit may be increased by .003 inches after lead finish is applied.

FIGURE 1. Case outlines – Continued.

Device type	01							
Case outlines	E	M	N	T	U	X	Y	2
Terminal number	Terminal symbol							
1	NC	GND	GND	GND	GND	NC	GND	NC
2	NC	OUTPUT	OUTPUT	INPUT	INPUT	NC	OUTPUT	NC
3	INPUT	INPUT	INPUT	OUTPUT	OUTPUT	NC	INPUT (CASE)	NC
4	NC	ISOLATED (CASE)	---	INPUT (CASE)	ISOLATED (CASE)	GND	---	NC
5	GND	---	---	---	---	NC	---	NC
6	OUTPUT	---	---	---	---	NC	---	GND
7	NC	---	---	---	---	OUTPUT	---	NC
8	NC	---	---	---	---	NC	---	NC
9	NC	---	---	---	---	NC	---	OUTPUT (SENSE)
10	NC	---	---	---	---	NC	---	NC
11	NC	---	---	---	---	NC	---	OUTPUT
12	NC	---	---	---	---	NC	---	OUTPUT
13	NC	---	---	---	---	NC	---	NC
14	NC	---	---	---	---	NC	---	NC
15	NC	---	---	---	---	NC	---	INPUT
16	NC	---	---	---	---	INPUT	---	INPUT
17	---	---	---	---	---	---	---	INPUT
18	---	---	---	---	---	---	---	NC
19	---	---	---	---	---	---	---	NC
20	---	---	---	---	---	---	---	NC

NC = No connection

FIGURE 2. Terminal connections.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.2.1 Additional criteria for device class M.

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.

(2) T_A = +125°C, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein.

4.2.2 Additional criteria for device classes Q and V.

a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.

b. Interim and final electrical test parameters shall be as specified in table II herein.

c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 Conformance inspection. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-PRF-38535 permits alternate in-line control testing. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 5, 6, 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance with MIL-PRF-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	---	---
Final electrical parameters (see 4.2)	1,2,3,4 1/	1,2,3,4 1/	1,2,3,4 1/
Group A test requirements (see 4.4)	1,2,3,4	1,2,3,4	1,2,3,4
Group C end-point electrical parameters (see 4.4)	1	1,2,3,4	1,2,3,4
Group D end-point electrical parameters (see 4.4)	1	1,2,3,4	1,2,3,4
Group E end-point electrical parameters (see 4.4)	---	---	---

1/ PDA applies to subgroup 1.

4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table II herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

b. T_A = +125°C, minimum.

c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.

4.4.4 Group E inspection. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein).

a. End-point electrical parameters shall be as specified in table II herein.

b. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535 for the RHA level being tested. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38535, appendix A for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25°C ±5°C, after exposure, to the subgroups specified in table II herein.

c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor prepared specification or drawing.

6.1.2 Substitutability. Device class Q devices will replace device class M devices.

6.2 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

6.3 Record of users. Military and industrial users should inform Defense Supply Center Columbus when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0525.

6.4 Comments. Comments on this drawing should be directed to DSCC-VA , Columbus, Ohio 43216-5000, or telephone (614) 692-0674.

6.5 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 Sources of supply for device classes Q and V. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.

6.6.2 Approved sources of supply for device class M. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 99-09-07

Approved sources of supply for SMD 5962-95709 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN 1/	Vendor CAGE number	Vendor similar PIN 2/
5962-9570901MMA	3/	0M2990-15SMM
5962-9570901MNA	3/	0M2990-15NMM
5962-9570901MTA	3/	0M2990-15NTM
5962-9570901MUA	69210	0M2990-15STM
5962-9570901MYA	3/	0M2990-15NKM
5962-9570901M2A	3/	0M2990-15S2M
5962-9570901QEA	27014	LM2990J-15-QML
5962-9570901QXA	27014	LM2990WG-15-QML

1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed, contact the vendor to determine its availability.
2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
3/ Not available from an approved source of supply.

Vendor CAGE number	Vendor name and address
27014	National Semiconductor Corporation 2900 Semiconductor Drive P.O. Box 58090 Santa Clara, CA 95052-8090
69210	Omnirel Corporation 205 Crawford Street Leominster, MA 01453-2353